

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT
APPLICATION

In re: PATENT APPLICATION of:

Group Art Unit 1763

Inventor(s): OHMI et al.

Examiner: L. Alejandro Mulero

Appln. No.: 09 827,307

Atty. Dkt. P 0280043

EL00026CDC

Series Code ↑ Serial No. ↑

M#

Client Ref

Filed: April 6, 2001

Title: PLASMA PROCESSING APPARATUS AND
PLASMA PROCESSING METHODR
C
EDO NOT USE FOR PROVISIONAL,
DIVISIONAL, CIP OR DESIGN
APPLICATIONS, OR REEXAMINATION OF
PATENTS

Mail Stop RCE

Hon. Commissioner for Patents

PO Box 1450

Alexandria, VA 22313-1450

Date: May 30, 2003

RECEIVED
JUN 03 2003
TC 1700 H14
6/4/03
mw

Sir:

REQUEST FOR CONTINUED EXAMINATION (RCE) UNDER RULE 114

Please continue the examination of this application.

PREREQUISITESThis application was filed on/after June 8, 1995, is not abandoned, and no court action has been filed, or if filed, it has been terminated.An issue fee **has not been** paid (unless a petition under Rule 313(c)(2) is also being filed -- see item 4 below).**Prosecution has been closed as defined in Rule 114(b).****Reply to any outstanding action must be enclosed or previously filed.**

This application is entitled under Rule 114 to withdrawal of any outstanding finality or of any allowance plus a new action by the Examiner. Consideration on the merits of each submission (e.g., IDS, Amendment, new arguments, new evidence, but not appeal/reply briefs themselves) filed herewith is respectfully requested.

Please consider the following before the next Official Action:

1. Please ☒ enter ☐ do not enter the Amendment filed April 30, 2003 (copy attached)
2. ☐ The enclosed new Amendment
3. ☐ Consider the arguments in the appeal brief filed ___ and reply brief filed
4. ☐ The issue fee has been paid, but this RCE is based on Rule 313(c)(2). See enclosed petition.
5. ☐ The enclosed Information Disclosure Statement

☐ IDS Letter
☐ PTO-1449

☐ Cited Appln

☐ Foreign Search Report/OA
☐ Cited Documents
6. ☐ Please suspend action under Rule 103(c) for a period of ___ months (3 mos. Max) for which charge the required \$130 fee (fee code 098) to our Deposit Account (see below).
7. Petition is hereby made to extend the **original** due date of March 30, 2003 to
 cover the date this Request is filed. The total extension fee will be \$300 (the two
 month extension fee of \$410 less the first month extension fee which has already
 been paid. **PLEASE CHARGE** the requisite fee of \$300 to our Deposit Account
 (see below)

(1 mo)	\$110/\$55
(2 mos)	\$410/\$205
(3 mos)	\$930/\$465 + 300
8. **PLEASE CHARGE** the Rule 17(e) (RCE) filing fee of ☒ \$750 (lg. ent.) ☐ \$375 (sm. ent.) plus any
 deficiency and any other fee due now or later to our Deposit
 Account No. 03-3975 under Order No. 040258 / 0280043

NOTE: Rule 17(e) filing fee Cannot be deferred!
NO CLAIMS FEE REQUIRED unless you are
adding claims by box 2 Amendment in which case
cover this with PAT-120.

06/03/2003 AWONDAF1 00000046 033975 09827307

C# M#

01 EC-1801 750.00 CH

Pillsbury Winthrop LLP
Intellectual Property GroupP.O. Box 10500
McLean, VA 22102

By Atty: Dale S. Lazar

Reg. No. 28872

(703) 905-2000
Atty/Sec: DSL/ml

Sig:

Fax: (703) 905-2500
Tel: (703) 905-2126

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UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION OF

Confirmation No.: 4153

OHMI et al.

Group Art Unit: 1763

Appln. No.: 09/827,307

Examiner: L. Alejandro Mulero

Filed: April 6, 2001

Title: PLASMA PROCESSING APPARATUS AND PLASMA PROCESSING METHOD

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April 30, 2003

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AMENDMENT

Hon. Commissioner of Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed December 30, 2002, please amend the above identified application as follows:

IN THE CLAIMS:

Please enter amended claims 1 and 7 as follows:

1. (Twice Amended) A plasma processing apparatus comprising:

a first electrode;

a substrate configured to be subjected to a plasma, the substrate being positioned on

the first electrode;

a magnetic field generator configured to apply a static magnetic field to a surface of

the substrate to which the plasma process is applied; and